

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Qing Ma et al.

Title: DIRECT BUILD-UP LAYER ON AN ENCAPSULATED DIE PACKAGE

Docket No.: 884.792US1

Serial No.: 09/640,961

Filed: August 16, 2000

Due Date: N/A

Examiner: Sheila V. Clark

Group Art Unit: 2823

**MS Amendment**

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

We are transmitting herewith the following attached items (as indicated with an "X"):

X Information Disclosure Statement (2 pgs.), Form 1449 (2 pgs.), and copies of 15 cited documents.

If not provided for in a separate paper filed herewith, Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG & WOESSNER, P.A.

Customer Number 21186

By: 

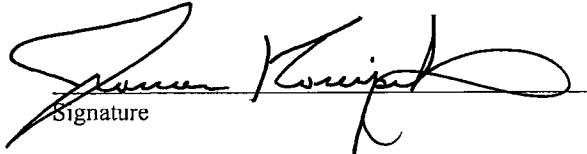
Atty: John N. Greaves

Reg. No. 40,362

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being filed using the USPTO's electronic filing system EFS-Web, and is addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 16th day of November, 2007.

James Kanyusik

Name

  
Signature

SCHWEGMAN, LUNDBERG & WOESSNER, P.A.

(GENERAL)